AIRSYS

Balance the Environment

2025 COMPANY OF THE YEAR

Driving impact across the customer value chain

RECOGNIZED FOR BEST PRACTICES IN THE NORTH AMERICAN DATA CENTER COOLING INDUSTRY

FROST & SULLIVAN

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Best Practices Criteria for World-Class Performance

Frost & Sullivan applies a rigorous analytical process to evaluate multiple nominees for each award category before determining the final award recipient. The process involves a detailed evaluation of best practices criteria across two dimensions for each nominated company. Airsys excels in many of the criteria in the data center cooling space.



Airsys: Pioneering Next-Generation Cooling Solutions

The rise of artificial intelligence (AI) is creating unprecedented capacity demands on data centers, emphasizing the need for advanced energy-efficient solutions capable of managing increasingly high-density environments. Data centers are significant carbon emitters, with cooling systems consuming up to 40% of their total energy to manage heat generated by information technology (IT) equipment.[1] While current methods like immersion cooling meet present heat density requirements, their reliance on complex infrastructure and substantial energy and water usage makes it challenging to scale for future high-density heat levels. These limitations highlight an urgent need for advanced cooling alternatives to support data centers as they expand to accommodate escalating IT loads, delivering reliability, enhanced uptime, and optimal performance while minimizing environmental impact.

Driven by the growing trend of high-density data center environments and a heightened focus on sustainability, Airsys is redefining information, communication, and technology thermal management. Its liquid cooling solutions, such as the LiquidRack™ and Adsorption Chiller, meet the critical need for energy-efficient cooling in high-heat density data centers while enhancing operational efficiency and reducing environmental impact.

[1] https://www.energy.gov/articles/doe-announces-40-million-more-efficient-cooling-data-centers

Developed by Airsys's Advanced Liquid Cooling Technologies (ALCT) division, these cutting-edge solutions offer exceptional scalability, maximize cooling efficiency, and enable full energy recovery by repurposing energy consumed by IT equipment for heating, cooling, and other applications. By delivering groundbreaking energy efficiency and superior cooling performance, Airsys -powered ALCT is redefining industry standards in energy conservation, reliability, scalability, and cost-effectiveness, positioning itself as an emerging pioneer in next-generation cooling technologies. Leveraging Airsys's established global manufacturing capabilities allows ALCT to accelerate innovation while optimizing production efficiency. Airsys's relocation of its global headquarters to South Carolina aligns with its strategy to meet the rising demand for advanced cooling solutions in high-density computing.

Airsys's LiquidRack™ utilizes a cutting-edge liquid spray cooling approach to manage the intense heat generated by high-density servers and processing units. It involves delivering a finely controlled coolant mist directly to the surface of critical components, such as central and graphics processing units. This direct contact method eliminates uneven thermal energy and accelerates heat removal. Liquid spray cooling supports higher power densities effectively, significantly reducing energy consumption associated with cooling systems while ensuring operational stability. This solution provides a sustainable cooling strategy for data centers aiming to reduce their carbon footprint and improve overall performance.

Airsys's liquid cooling solution utilizes a single-phase spray or impingement cooling method, delivering a superior heat transfer coefficient compared to immersion cooling. Grounded in the principles of forced convection, this advanced spray technique optimizes heat transfer efficiency by enhancing thermal exchange between the solid surface and the liquid in direct contact with it. Unlike immersion cooling, which depends on natural convection, this approach enhances thermal management through forced convection, enabling superior high-density heat rejection for greater cooling efficiency. Moreover, Airsys's liquid spray cooling solution enables complete heat recovery, empowering energy-efficient data centers. Engineered for seamless integration with existing infrastructure and minimal maintenance, the system offers a cost-effective solution that facilitates installation without additional expenses and ensures effortless upkeep to maintain optimal performance.

Revolutionizing Thermal Management for High-Performance GPUs

As AI applications expand, the demand for powerful graphics processing units (GPUs) has surged, driving unprecedented power consumption and density requirements. The rapid advancement of GPUs over the past two years has led to a dramatic rise in power consumption; for example, Nvidia has reported a 75% increase in power usage within a single generation of its GPUs. The H100 with SXM has a power consumption of up to 700 watts (W), significantly higher than its A100 SXM version, which consumes 400 W. Current data center infrastructure, limited to supporting 1.5 kilowatts (kW) per SXM slot, will inevitably face challenges with next-generation GPUs, such as Nvidia's forthcoming Blackwell series, which is expected to consume up to 2.7 kW. To accommodate these advanced GPUs, data centers must upgrade their power delivery, cooling capacity, and physical space to meet high-performance hardware thermal and energy demands.

As next-generation GPUs push the boundaries of power and cooling, Airsys sets itself apart with its innovative 3D-printed, two-phase microchannel heat sinks, engineered to tackle these challenges. Specifically designed for high-density, high-power GPUs, this advanced solution optimizes heat rejection

and reuse, ensuring superior thermal management and energy efficiency. In recent laboratory tests, the technology demonstrated heat rejection capacity exceeding 2 kW on a surface area of 5.5 x 2.7 inches.[2] When the heat density gets scaled to the surface area of an SMX5 socket (the current H100 socket), the thermal design power (TDP) can exceed 10 kW, demonstrating its capability to seamlessly support next-generation GPUs.[3]

Beyond its high-heat density performance, this compact, waterless, two-phase cooling system overcomes the limitations of traditional liquid-cooling solutions by delivering exceptional efficiency, minimal resource consumption, and a reduced footprint. The technology prioritizes heat reuse, promoting sustainable operations by redirecting and repurposing waste heat, thereby enhancing data center energy efficiency. Furthermore, by leveraging 3D printing, Airsys enables customers to keep pace with the rapid iterations in chip technology, addressing the ongoing need for multiple heat sink redesigns and retooling. With 3D printing, Airsys enables rapid adaptations to evolving GPU designs, ensuring high-quality standards through precision manufacturing while minimizing logistical challenges. Overall, 3D printing offers low CAPEX, agility, scalability, and enhanced supply chain security, making it an effective solution for data centers responding to the fast-evolving AI and GPU technologies.

Airsys is consistently pushing thermal barriers and enhancing heat recovery capabilities. In response to the increasing demands for effective thermal management, Airsys has successfully exceeded the 2 kW TDP limit in the lab. It is set to launch next-generation cooling solutions by Q1 2025, capable of handling thermal loads of up to 3 kW TDP per chip. Designed to support high-performance processors, these solutions deliver unmatched cooling efficiency for the most demanding computing environments. Airsys's advanced heat sink design operates at saturated temperatures of up to 60°C, optimizing the system for effective heat recovery and reuse. This innovative approach addresses thermal demands while enhancing energy efficiency by allowing data centers to redirect waste heat, promoting more sustainable operations. Airsys's high-density, heat-recovery cooling solution significantly surpasses current requirements, demonstrating its capacity to address future thermal challenges while minimizing environmental impact.

Driving Industry Transformation with Cutting-Edge Innovations

Airsys builds on proven fundamentals and engineering principles to develop high-performance cooling solutions, dramatically enhancing high-density cooling efficiency. The company conducts in-depth evaluations of different cooling methods, including the two primary two-phase systems—pool boiling and flow boiling—to optimize thermal management strategies. By thoroughly analyzing these approaches, Airsys optimizes its designs to deliver superior thermal management solutions that are efficient, reliable, and scalable. Importantly, its solutions are well-prepared to meet the demands of future generations of high-performance electronics and advanced cooling applications, such as its two-phase, microchannel, 3D-printed heat sink.

By recognizing the limitations of pool boiling (i.e., a liquid-filled heat sink on a central processing unit (CPU) that forms vapor bubbles when liquid heats up) for high-power applications, Airsys opted for flow boiling. Combining nucleate and convective boiling, flow boiling allows liquid to flow continuously through

[2] Frost & Sullivan Interview with Airsys, October 2024
[3] Ibid.

a heated channel or tube, resulting in a more stable and efficient cooling mechanism. Unlike pool boiling, which can only manage a limited heat load, flow boiling integrates two effective heat transfer methods to achieve a high and stable heat transfer rate under demanding conditions, making it ideal for high-performance computers. Additionally, pool boiling faces challenges with vapor transport due to its reliance on passive movement rather than a pump-driven mechanism, which can hinder vapor return to the condenser. This limitation often necessitates larger channels or vacuum systems to facilitate vapor flow, adding complexity to the design.

Through further examination of injection systems and channel designs, Airsys identified the limitations of single-phase injection systems and traditional microchannel and microchannel designs. While single-phase injection systems achieve high heat transfer by directing microjets onto heated surfaces, their small orifices, essential for efficient cooling, are susceptible to clogging. This can lead to flow imbalances, potentially compromising performance and reliability. Moreover, these systems are susceptible to erosion due to the high-velocity impact of the jets, which can cause surface degradation over time, diminishing the cooling surface lifespan. Also, despite microchannels providing excellent heat transfer through their compact flow paths, they present challenges such as significant pressure drops and the need for substantial pumping power. Additionally, the small dimensions of microchannels increase the risk of flow choking, which can adversely impact stability and overall cooling efficiency.

To overcome these challenges, Airsys employs a central (axial) impingement design with radially curved microchannels that enhance heat transfer efficiency while minimizing the risks associated with single-phase systems and traditional microchannel designs. This approach allows refrigerants to enter axially, ensuring even distribution across the surface with high-velocity jets. The curved microchannels facilitate smooth flow, reducing the risk of clogging and improving vapor removal. Additionally, the diverged microchannel design minimizes rapid pressure drop, and the intermittent fin design reduces pressure fluctuations, stabilizing liquid flow. These innovative mechanical designs result in a robust and efficient cooling solution that effectively meets the demands of high-density applications.

By leveraging advanced 3D printing technology for heat sink manufacturing, Airsys unlocks significant performance and efficiency advantages, optimizing thermal management for next-generation cooling solutions. Besides providing greater design flexibility, which enables extensive customization and complex geometric designs, the company empowers rapid prototyping, expediting development cycles. Additionally, its streamlined manufacturing process eliminates the time- and resource-intensive steps of traditional manufacturing, removing the need for separate part production and assembly. Moreover, 3D printing enhances quality control by reducing critical flaws that could compromise performance, such as leaks. Leveraging 3D printing's automated, 24/7 production capabilities also lowers labor costs and overall expenses, making it a cost-effective solution. Additionally, 3D printing empowers localized production, minimizes supply chain risks, reduces lead times, and improves response times to customer inquiries. Overall, 3D printing allows for efficient, precise, and environmentally sustainable production. This approach allows for rapid iterations in response to advancements in chip technology, supporting efficient thermal management solutions and enhancing scalability in high-performance computing.

Specifically engineered for high-density GPU applications, the two-phase microchannel heat sink delivers exceptional cooling performance, removing up to 2030 W of heat while maintaining a case temperature

of just 79°C.[4] It excels in heat recovery, dissipating 1800 W at a water inlet temperature of 50°C and a 15 K subcooling.[5]

Harnessing Technology to Drive Best Practice Excellence

> *"As next-generation GPUs push the boundaries of power and cooling, Airsys sets itself apart with its innovative 3D-printed, two-phase microchannel heat sinks, engineered to tackle these challenges. Specifically designed for high-density, high-power GPUs, this advanced solution optimizes heat rejection and reuse, ensuring superior thermal management and energy efficiency."*
>
> ***Gautham Gnanajothi***
> ***Global Vice President of Research***

Airsys prioritizes innovative design elements, balancing efficient and sustainable design principles centered on precision, optimal performance, energy efficiency, and reduced waste. A testament to Airsys's engineering excellence is its patented spray liquid cooling solution, LiquidRack™. This cutting-edge innovation incorporates advanced design features to maximize cooling performance, optimize resource utilization, and enhance energy efficiency, setting a new benchmark in next-generation cooling technology. Notably, it features a 3D-printed sprayer with customized orifices strategically positioned to provide full coverage over the inclined heat sink. Tailored to match the heat sink design and unique characteristics (e.g., heat load requirements, geometrical size requirements, and internal space requirements within a chassis), the 3D-printed sprayer facilitates precise coolant delivery. Additionally, the inclined heat sink guarantees 100% even distribution of the sprayed cooling liquid across the entire surface, including the bottom rack. Recognizing the limitations of horizontal cooling systems, Airsys designed the LiquidRack™, so servers are positioned vertically within the rack, leveraging gravity to ensure complete liquid drainage and prevent fluid accumulation around components. Overall, these features maximize heat transfer efficiency, promoting effective cooling and ensuring optimal utilization of the cooling fluid, eliminating the need for excess pump power to compensate for wasted fluid.

Airsys's LiquidRack™ achieves a high cooling density of 14 units (U) x2, delivering an impressive cooling rate of 1 kilowatt (kW)/U, with each liquid rack capable of scaling up to a total cooling capacity of 200 kW.[6] While providing powerful cooling, Airsys' LiquidRack™ uses only 20% of the cooling liquid required by immersion cooling systems, ensuring highly efficient resource use.[7] Additionally, the full coverage provided by the 3D printed sprayer over the heat sink, prevents oil vapor from escaping, a common problem with immersion cooling systems. By effectively containing coolant within the coverage area, Airsys' design mitigates bad odor and reduces evaporation. Additionally, it reduces electronic safety risks associated with vapors condensing on cold surfaces, which can attract dust and contaminants, potentially leading to equipment failure. Furthermore, oil mist generation can trigger fire safety alerts, posing challenges for fire permit approvals in older data centers not originally designed for immersion cooling. Airsys' commitment to efficient design enhances cost-effectiveness, accelerates deployment, and simplifies operations and maintenance, emphasizing customizability, compatibility, accessibility, and

[4] Ibid.
[5] Ibid.
[6] Frost & Sullivan Interview with Airsys, October 2024
[7] https://airsysnorthamerica.com/liquidrack/

seamless integration. Its highly configurable sprayer adapts to various heat sinks, heat loads, and server models, enabling customers to maintain their existing system configurations, thus saving costs. It also supports versatile configurations, allowing the LiquidRack™ to be customized for specific requirements, such as accommodating 1 kW, 2 kW, and 3 kW servers in the same tank with a spray solution that balances liquid supply to each server, ideal for colocation applications.

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> ***Global Vice President of Research***

With a one-to-two-day design and prototyping turnaround, the 3D sprayer speeds up implementation compared to immersion cooling, which demands extensive testing for various heat sinks and configurations. For enhanced accessibility, servers are mounted on lockable slides, allowing them to be securely positioned at the middle or top for easy access during operations and maintenance. Additionally, all other critical components are conveniently accessible from the front, ensuring seamless servicing and operational efficiency.

Complementing its engineering principles, Airsys incorporates cutting-edge technologies to enhance performance and reliability. For instance, dual permanent magnet DC pumps offer 20,000 hours of service each, providing a total of 40,000 hours of reliability with an n + 1 setup for rotation. Furthermore, it features a phase change heat exchanger, which efficiently transfers heat and enhances cooling performance.

The Airsys Commitment: Exceptional Outcomes, Enduring Trust

Airsys' LiquidRack™ excels in high-density cooling performance, addressing the increasing power demands of modern data centers.Its innovative design demonstrates significant advantages over conventional methods, such as immersion cooling. In a test conducted using a heat sink the size of Dell 02k16D, at a utility water inlet temperature of 35°C, the LiquidRack™ achieved a heat rejection capacity of 1.8 kW and exceptional thermal transfer performance, effectively cooling components with case temperatures up to 85°C.[8] Consequently, it significantly reduced the thermal resistance to 0.027°C/W. In a following test based on the current data center utility water inlet temperature of 25°C, the solution delivers up to 2.2 kW heat rejection.[9]The test result demonstrates LiquidRack™'s high-density cooling capabilities for upcoming high-performance GPUs. Additionally, with a power consumption of only 50 W, less than that of two standard aisle cooling fans, the liquid cooling solution achieves a power usage effectiveness (PUE) of approximately 1.02.[10]

Airsys LiquidRack™ maximizes data center energy efficiency through its advanced full heat recovery capability, capturing waste heat from IT equipment and repurposing it for additional energy applications. Using the same Dell 02K16D heat sink at an elevated outlet water temperature of 60°C, the Airsys LiquidRack™ enables high-grade heat recovery while keeping case temperatures of 740W CPUs (based on

[8] Ibid.
[9] Ibid.
[10] Ibid.

the majority current CPU range) below 80°C.[11] This heat resistance extends to high-end, larger-form GPUs, ensuring reliable recovery and performance. Furthermore, being fully insulated, the LiquidRack™ prevents heat leakage into the ambient environment, eliminating the need for additional air conditioning units in the data hall.

Moreover, the hot outlet water can be redirected to Airsys's Adsorption Chiller, which can generate chilled water at 20°C, to be reused in data center air handlers, enhancing water efficiency.[12] The LiquidRack™'s dual functionality allows customers to meet the high-density cooling demands of future GPUs, with maximum capacities of 2.2 kW, while simultaneously supporting heat recovery and water optimization initiatives.[13] With its flexible design, the LiquidRack™ can be tailored to specific customer cooling requirements by configuring the sprayer and hydrodynamic systems based on unique heat sink attributes. This versatility allows Airsys to adapt to diverse market demands, delivering optimal cooling performance while maximizing efficient heat recovery. This full spectrum of capabilities positions Airsys as a leader in innovative cooling solutions that seamlessly connect high-performance computing with sustainable energy recovery.

Airsys LiquidRack™ optimizes data center space with a vertical, service-friendly design that integrates effortlessly into existing setups. With front and back access to all components, the system ensures seamless accessibility during operations and enables quick, dry server maintenance without requiring additional equipment. Unlike immersion tanks, which demand extra base reinforcement due to their substantial liquid coolant capacity, this design eliminates the need for additional structural support, enhancing installation flexibility and efficiency. The minimal coolant charge also lowers fire risks and minimizes environmental impact. Dripless connectors and top-to-bottom piping enable direct utility water connection, removing the need for cooling towers and simplifying installation. The system achieves 100% free cooling without chillers, even at 50°C ambient temperatures, avoiding water usage and treatment issues.[14] Its fully sealed, insulated tanks and integrated heat recovery capabilities support district heating connections, enhancing energy efficiency and sustainability. Compliant with Open Compute Project guidelines, LiquidRack™ offers a modular, standardized design that allows quick response to customer requirements, short lead times, and the flexibility to easily scale up complete solutions at reduced capital expenditure (CAPEX) and total cost of ownership.

Sustainable Cooling Reinvented: The Power of Airsys Adsorption Chiller

Airsys amplifies energy and water efficiency with its latest innovation, the Adsorption Chiller, which captures waste heat to produce cold water or usable electricity. The technology functions through a three-phase cycle: absorption, pre-heating and pre-cooling, and desorption. Initially, moisture from the air is absorbed, then condensed back into liquid. Upon heating, the trapped moisture is released, creating a cooling effect by absorbing and dissipating heat. The final stage regenerates the adsorbent, ensuring continuous and efficient operation for the next cycle.

[11] Ibid.
[12] Ibid.
[13] Ibid.
[14] Ibid.

By integrating the Adsorption Chiller and Airsys LiquidRack™, data centers can optimize heat removal from computing hardware. The hybrid solution directly targets primary heat sources, reducing the overall energy required for cooling and significantly improving data center PUE. Moreover, utilizing waste heat for adsorption cooling, maximizes energy efficiency, contributing to sustainable data center operations. This degree of energy recapture and reuse is unattainable with immersion cooling, which fails to capture sufficient heat to lower energy demand throughout the cooling process or contribute to meaningful heat recovery initiatives. Furthermore, the cool water produced by the adsorption cooling process can be reused as chilled water in data center air handlers reducing the liquid from 50+°C to 16-20°C.[15] By enhancing cooling efficiency and energy reuse, the Adsorption Chiller can drive PUE levels theoretically below 1.0, achieving ultra-efficient data center performance.[16] By incorporating Adsorption Chiller into its liquid cooling solution, Airsys maximizes energy regeneration, driving efficient use of waste heat or solar energy. This approach significantly reduces electricity demand and reliance on harmful refrigerants, optimizing PUE and water usage effectiveness. As a result, Airsys delivers substantial energy savings, allowing customers to expand AI capabilities without increasing their energy footprint.

Conclusion

As AI-driven workloads push data centers to their thermal limits, the demand for greater energy and water efficiency has never been more critical. Airsys, driven by innovation and industry best practices, is addressing these challenges head-on with advanced cooling solutions like LiquidRack™, a two-phase microchannel 3D-printed heat sink, and Adsorption Chiller technologies. These cutting-edge solutions are redefining industry standards, delivering superior cooling performance, maximizing energy and water efficiency, enabling full energy recovery, and minimizing environmental impact.

With a steadfast focus on cost-effectiveness, seamless deployment, streamlined operations, and tailored solutions, Airsys ensures unmatched customer support. Through its relentless commitment to excellence, the company continues to set new benchmarks, reinforcing its position as a pioneer in data center cooling.

With its strong overall performance, Airsys earns Frost & Sullivan's 2025 North American Company of the Year Award in the data center cooling industry.

[15] Frost & Sullivan Interview with Airsys, October 2024
[16] Ibid.

What You Need to Know about the Company of the Year Recognition

Frost & Sullivan's Company of the Year Award is its top honor and recognizes the market participant that exemplifies visionary innovation, market-leading performance, and unmatched customer care.

Best Practices Award Analysis

For the Company of the Year Award, Frost & Sullivan analysts independently evaluated the criteria listed below.

Visionary Innovation & Performance

Addressing Unmet Needs: Customers' unmet or under-served needs are unearthed and addressed by a robust solution development process

Visionary Scenarios Through Mega Trends: Long-range, macro-level scenarios are incorporated into the innovation strategy through the use of Mega Trends, thereby enabling first-to-market solutions and new growth opportunities

Leadership Focus: Company focuses on building a leadership position in core markets and on creating stiff barriers to entry for new competitors

Best Practices Implementation: Best-in-class implementation is characterized by processes, tools, or activities that generate a consistent and repeatable level of success

Financial Performance: Strong overall business performance is achieved in terms of revenue, revenue growth, operating margin, and other key financial metrics

Customer Impact

Price/Performance Value: Products or services provide the best value for the price compared to similar market offerings

Customer Purchase Experience: Quality of the purchase experience assures customers that they are buying the optimal solution for addressing their unique needs and constraints

Customer Ownership Experience: Customers proudly own the company's product or service and have a positive experience throughout the life of the product or service

Customer Service Experience: Customer service is accessible, fast, stress-free, and high quality

Brand Equity: Customers perceive the brand positively and exhibit high brand loyalty

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Best Practices Recognition Analytics Methodology

Inspire the World to Support True Leaders

This long-term process spans 12 months, beginning with the prioritization of the sector. It involves a rigorous approach that includes comprehensive scanning and analytics to identify key best practice trends. A dedicated team of analysts, advisors, coaches, and experts collaborates closely, ensuring thorough review and input. The goal is to maximize the company's long-term value by leveraging unique perspectives to support each Best Practice Recognition and identify meaningful transformation and impact.

		VALUE IMPACT	
STEP		WHAT	WHY
1	**Opportunity Universe**	Identify Sectors with the Greatest Impact on the Global Economy	Value to Economic Development
2	**Transformational Model**	Analyze Strategic Imperatives That Drive Transformation	Understand and Create a Winning Strategy
3	**Ecosystem**	Map Critical Value Chains	Comprehensive Community that Shapes the Sector
4	**Growth Generator**	Data Foundation That Provides Decision Support System	Spark Opportunities and Accelerate Decision-making
5	**Growth Opportunities**	Identify Opportunities Generated by Companies	Drive the Transformation of the Industry
6	**Frost Radar**	Benchmark Companies on Future Growth Potential	Identify Most Powerful Companies to Action
7	**Best Practices**	Identify Companies Achieving Best Practices in All Critical Perspectives	Inspire the World
8	**Companies to Action**	Tell Your Story to the World (BICEP*)	Ecosystem Community Supporting Future Success

*Board of Directors, Investors, Customers, Employees, Partners

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About Frost & Sullivan

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The Growth Pipeline Engine™

Frost & Sullivan's proprietary model to systematically create ongoing growth opportunities and strategies for our clients is fuelled by the Innovation Generator™.
Learn more.

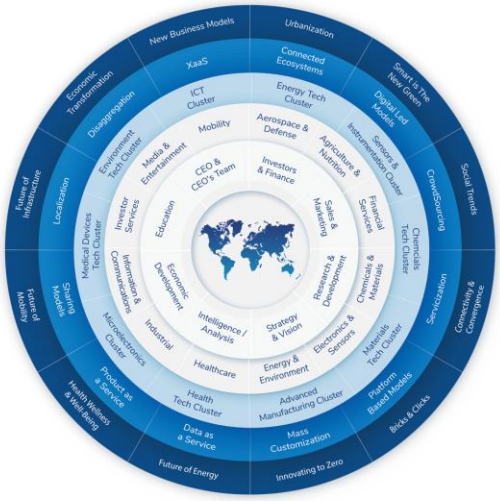


Key Impacts:

- **Growth Pipeline:** *Continuous Flow of Growth Opportunities*
- **Growth Strategies:** *Proven Best Practices*
- **Innovation Culture:** *Optimized Customer Experience*
- **ROI & Margin:** *Implementation Excellence*
- **Transformational Growth:** *Industry Leadership*

The Innovation Generator™

Our 6 analytical perspectives are crucial in capturing the broadest range of innovative growth opportunities, most of which occur at the points of these perspectives.



Analytical Perspectives:

- Mega Trend (MT)
- Business Model (BM)
- Technology (TE)
- Industries (IN)
- Customer (CU)
- Geographies (GE)